



Material Content Data Sheet



Sales Product Name				TDA21220		Issued		28. August 2013	
MA#				MA001012762					
Package				PG-IQFN-40-1		Weight*		100.11 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.536	1.53	1.53	15343	15343	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		127		
	non noble metal	zinc	7440-66-6	0.051	0.05		510		
	non noble metal	iron	7439-89-6	1.020	1.02		10191		
wire	non noble metal	copper	7440-50-8	41.428	41.37	42.45	413809	424637	
	noble metal	gold	7440-57-5	0.308	0.31	0.31	3073	3073	
encapsulation	organic material	carbon black	1333-86-4	0.086	0.09		856		
	plastics	epoxy resin	-	4.415	4.41		44100		
	inorganic material	silicondioxide	60676-86-0	38.363	38.32	42.82	383203	428159	
leadfinish	non noble metal	tin	7440-31-5	1.567	1.57	1.57	15657	15657	
plating	noble metal	silver	7440-22-4	1.920	1.92	1.92	19181	19181	
glue	plastics	epoxy resin	-	0.093	0.09		931		
	noble metal	silver	7440-22-4	0.280	0.28	0.37	2792	3723	
solder	non noble metal	tin	7440-31-5	0.028	0.03		284		
	noble metal	silver	7440-22-4	0.036	0.04		355		
	non noble metal	lead	7439-92-1	1.357	1.36	1.43	13555	14194	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		20		
	non noble metal	zinc	7440-66-6	0.008	0.01		82		
	non noble metal	iron	7439-89-6	0.164	0.16		1636		
	noble metal	silver	7440-22-4	0.787	0.79		7860		
	non noble metal	copper	7440-50-8	6.651	6.64	7.60	66435	76033	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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